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Spansion Selects SOKUDO's RF^{3S} System for 32 nm Immersion Lithography Processing

SUNNYVALE, California, KYOTO, Japan — February 21, 2008 — Spansion, a leading Flash memory solutions provider, has selected the new RF^{3S} coat/develop track system from SOKUDO Co., Ltd. to develop 193 nm immersion processes for its leading-edge 32 nm Flash devices. The RF^{3S} system was delivered to Spansion's Submicron Development Center (SDC) in Sunnyvale, CA, late 2007.

"We have performed a thorough evaluation of available track tools to support Spansion's second generation immersion lithography technology and have selected the RF^{3S} based on its exceptional performance and competitive cost," said John Behnke, Vice President of Process Development and Transfer at Spansion. "This alliance demonstrates the industry's growing need for early collaboration. The close proximity of the SDC, which is the only full-flow 300 mm process/product development line in the Silicon Valley, to SOKUDO's development site at Applied Materials' Maydan Technology Center, will serve to strengthen the effectiveness of our development teams. We look forward to working together with SOKUDO to develop our next generations of world-class Flash technology to meet the expanding needs and challenges of our customers."

SOKUDO's RF^{3S} system demonstrated <1.0 nm, 3 sigma critical dimension (CD) uniformity on a 45 nm CD and immersion defect density of <0.1 defects/cm². Technologists from the SDC and SOKUDO will collaborate to fully optimize the performance of the second generation immersion lithography cell to meet the increased patterning and manufacturing challenges at the 32 nm node and beyond. The Spansion-SOKUDO team will take advantage of the RF^{3S} system's integrated defect reduction technology to take immersion lithography to new levels of cleanliness required for 32 nm.

According to Takashige Suetake, CEO of SOKUDO, "This agreement will provide SOKUDO with an opportunity to qualify our immersion technology for leading Flash memory applications. We are excited to be working with Spansion and believe that this collaboration will help to ensure that benchmark process and immersion defect control is available for 32 nm immersion processes."

Spansion is a leading Flash memory solutions provider, dedicated to enabling, storing and protecting digital content in wireless, automotive, networking and consumer electronics applications. Spansion, previously a joint venture of AMD and Fujitsu, is the largest company in the world dedicated exclusively to designing, developing, manufacturing, marketing and selling Flash memory solutions. For more information, visit www.spansion.com.

SOKUDO Co., Ltd., headquartered in Kyoto, Japan, is a joint venture company owned by Dainippon Screen Mfg. Co., Ltd. and Applied Materials, Inc. SOKUDO was established on July 3, 2006 for the development, manufacturing, sales and service of advanced coat/develop track equipment for semiconductor production. Further information on SOKUDO can be found at www.sokudo.com.

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